DM81x Design Network Partners

Category	Expertise	Design Network Member	Specialty	Region	Contact
SW development	System SW OS (Windows®, Linux™)	Adeneo	Windows Embedded, BSP / EVM	EU – France, AM	Yannick Chammings ychammings@adeneoembedded.com
SW development	OS (Windows, Linux) M3 customization for HDVPSS and ISS	MPC Data	Complete Windows Embedded and Linux bring-up M3 source code for customization	UK, AM	Morten lversen morteni@bsquare.com
SW development	System SW	Sasken	Android [™] and multimedia	WW	Prashanth Bhushan Prashanth.bhushan@sasken.com
SW development	Multimedia G-Streamer	Collabora	World's leading provider of consulting, development and training for G-Streamer	UK	Robert McQueen robert.mcqueen@collabora.co.uk
SW development	Multimedia G-Streamer	SolDel Group	Complete Linux bring-up, G-Streamer	UK	Christian Pennycate cjp@soldelgroup.com
SW & HW development	M3 customization for HDVPSS and ISS HW design	Nexvision	High-end video and imaging systems M3 source code for customization	France	Vincent Carrier vincent.carrier@nexvision.fr
SW development	ISS tuning	MMS	Delivering innovation in multimedia and imaging for mobile phone market (ISP, camera)	Bulgaria	Nikolai Daskalov ndaskalov@mm-sol.com
SW development	Codecs	Ittiam	Video infrastructure	France / India	Denis Castaing denis.castaing@ittiam.com
SW development	Codecs	Path Partner	Video and vision applications	India	Ramkishor Korada ramkishor.korada@pathpartnertech.com
HW & SW development	HW/SW development	Mistral	HW and SW development	USA / India	Samyeer Metrani samyeer@mistralsolutions.com
Modules	DM8148	AIT	Qseven® – Module 70mm×70mm, ISIF connector	Austria	Knorr Johannes Johannes.Knorr@ait.ac.at
HW & SW development	DM8148, DM8168	elnfochips	Product design, board bring-up, reference platform design, SOM, system software development, video applications	USA / India	Ajatshatru Dhawal ajat.dhawal@einfochips.com ti.marketing@einfochips.com
Modules	DM8148	Dave	SOM	Italy	Manuele Papais manuele.papais@dave.eu
Modules	DM8148, DM8168	Z3 Technologies	SOM	USA / India	Aaron Caldwell aaroncaldwell@z3technology.com
Modules	DM8168	IMP	Qseven® – Module 70mm×70mm, ISIF connector	Serbia	Nikola Nenadic nikola.nenadic@pupin.rs

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products Applications

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive Communications and Telecom Amplifiers amplifier.ti.com www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps

DSP **Energy and Lighting** dsp.ti.com www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical logic.ti.com Logic Security www.ti.com/security

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers <u>microcontroller.ti.com</u> Video and Imaging <u>www.ti.com/video</u>

RFID <u>www.ti-rfid.com</u>

OMAP Applications Processors www.ti.com/omap TI E2E Community e2e.ti.com/omap

Wireless Connectivity <u>www.ti.com/wirelessconnectivity</u>